THIS IS NOT AN IMPEDANCE CONTROLLED BOARD

Drill Table

<table>
<thead>
<tr>
<th>ID</th>
<th>Location</th>
<th>Material</th>
<th>Type</th>
<th>Tolerances</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>Holes</td>
<td>Copper</td>
<td>Round</td>
<td>±0.005 mm</td>
</tr>
<tr>
<td>B</td>
<td>Holes</td>
<td>Copper</td>
<td>Round</td>
<td>±0.010 mm</td>
</tr>
<tr>
<td>C</td>
<td>Holes</td>
<td>Copper</td>
<td>Round</td>
<td>±0.015 mm</td>
</tr>
<tr>
<td>D</td>
<td>Holes</td>
<td>Copper</td>
<td>Round</td>
<td>±0.020 mm</td>
</tr>
</tbody>
</table>

Tolerances:
- For 7.67 mil via ±0.07 mil
- For 10 mil via ±0.10 mil
- For 12 mil via ±0.12 mil
- For PTH ±0.3 mil
- For PTH ±0.5 mil

All artwork viewed from top side.

Board No: TIDM-06332
Rev: E2
S/N: 13

Layer Name: Drill Drawing

Plot Name: Drill Drawing

Generated: 6-21-2019 3:50:30 PM

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